

# *DIODES*

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# Periodic Table of Elements

## Periodic table of the elements

period	group 1*	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
1	1 <b>H</b>																	2 <b>He</b>
2	3 <b>Li</b>	4 <b>Be</b>											5 <b>B</b>	6 <b>C</b>	7 <b>N</b>	8 <b>O</b>	9 <b>F</b>	10 <b>Ne</b>
3	11 <b>Na</b>	12 <b>Mg</b>											13 <b>Al</b>	14 <b>Si</b>	15 <b>P</b>	16 <b>S</b>	17 <b>Cl</b>	18 <b>Ar</b>
4	19 <b>K</b>	20 <b>Ca</b>	21 <b>Sc</b>	22 <b>Ti</b>	23 <b>V</b>	24 <b>Cr</b>	25 <b>Mn</b>	26 <b>Fe</b>	27 <b>Co</b>	28 <b>Ni</b>	29 <b>Cu</b>	30 <b>Zn</b>	31 <b>Ga</b>	32 <b>Ge</b>	33 <b>As</b>	34 <b>Se</b>	35 <b>Br</b>	36 <b>Kr</b>
5	37 <b>Rb</b>	38 <b>Sr</b>	39 <b>Y</b>	40 <b>Zr</b>	41 <b>Nb</b>	42 <b>Mo</b>	43 <b>Tc</b>	44 <b>Ru</b>	45 <b>Rh</b>	46 <b>Pd</b>	47 <b>Ag</b>	48 <b>Cd</b>	49 <b>In</b>	50 <b>Sn</b>	51 <b>Sb</b>	52 <b>Te</b>	53 <b>I</b>	54 <b>Xe</b>
6	55 <b>Cs</b>	56 <b>Ba</b>	57 <b>La</b>	72 <b>Hf</b>	73 <b>Ta</b>	74 <b>W</b>	75 <b>Re</b>	76 <b>Os</b>	77 <b>Ir</b>	78 <b>Pt</b>	79 <b>Au</b>	80 <b>Hg</b>	81 <b>Tl</b>	82 <b>Pb</b>	83 <b>Bi</b>	84 <b>Po</b>	85 <b>At</b>	86 <b>Rn</b>
7	87 <b>Fr</b>	88 <b>Ra</b>	89 <b>Ac</b>	104 <b>Rf</b>	105 <b>Db</b>	106 <b>Sg</b>	107 <b>Bh</b>	108 <b>Hs</b>	109 <b>Mt</b>	110 <b>Ds</b>	111 <b>Rg</b>	112 <b>Cn</b>	113 <b>Nh</b>	114 <b>Fl</b>	115 <b>Mc</b>	116 <b>Lv</b>	117 <b>Ts</b>	118 <b>Og</b>
lanthanoid series 6	58 <b>Ce</b>	59 <b>Pr</b>	60 <b>Nd</b>	61 <b>Pm</b>	62 <b>Sm</b>	63 <b>Eu</b>	64 <b>Gd</b>	65 <b>Tb</b>	66 <b>Dy</b>	67 <b>Ho</b>	68 <b>Er</b>	69 <b>Tm</b>	70 <b>Yb</b>	71 <b>Lu</b>				
actinoid series 7	90 <b>Th</b>	91 <b>Pa</b>	92 <b>U</b>	93 <b>Np</b>	94 <b>Pu</b>	95 <b>Am</b>	96 <b>Cm</b>	97 <b>Bk</b>	98 <b>Cf</b>	99 <b>Es</b>	100 <b>Fm</b>	101 <b>Md</b>	102 <b>No</b>	103 <b>Lr</b>				

\*Numbering system adopted by the International Union of Pure and Applied Chemistry (IUPAC).

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## Characteristics And properties of Semiconductors

- **Solid-state devices** to vacuum tubes in most applications are their **small size and weight, low operating voltage , lower power dissipation, higher reliability and extremely long life.**
- There is no warm up-period required since semiconductors are **absent a cathode heater.**
- Semiconductors typically do not perform as well as vacuum tube for high power, high frequency operation, such as television broadcasting and they are much more vulnerable to electro-static discharge during handling and operation.

## SEMICONDUCTOR MATERIAL

	III	IV	V	VI
	5 <b>B</b> 10.81	6 <b>C</b> 12.01	7 <b>N</b> 14.01	8 <b>O</b> 16.00
	13 <b>Al</b> 26.98	14 <b>Si</b> 28.09	15 <b>P</b> 30.97	16 <b>S</b> 32.06
30 <b>Zn</b> 65.38	31 <b>Ga</b> 69.72	32 <b>Ge</b> 72.59	33 <b>As</b> 74.92	34 <b>Se</b> 78.96
48 <b>Cd</b> 112.40	49 <b>In</b> 114.80	50 <b>Sn</b> 118.70	51 <b>Sb</b> 121.80	52 <b>Te</b> 127.60

### Group IV

- element such as Carbon (C), Silicon (Si), Germanium (Ge), Tin (Sn) are known as elemental or single – element semiconductors.
- Ge was widely used on early ; however its thermal sensitivity makes it less useful than silicon.
- Ge is often combined with silicon to make **very high-speed silicon-germanium(SiGe)** devices.
- Silicon is often combined with Carbon to form **Silicon-Carbon(SiC)** devices for **high power and high temperature application.**

➤ Compound Semiconductors that can be synthesized using elements from 3<sup>rd</sup> and 5<sup>th</sup> group of periodic table like:

- Gallium-Arsenide(GaAs)
- Gallium-Phosphide(GaP)
- Gallium-Nitride(GaN)
- Gallium-Aluminum-Arsenide(GaAlAs)
- Indium-Phosphorus(InP)
- Indium-Antimony(InSb)

	III	IV	V	VI
	5 <b>B</b> 10.81	6 <b>C</b> 12.01	7 <b>N</b> 14.01	8 <b>O</b> 16.00
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The Color of light that emits from a Light Emitting Diode depends on which of these compounds are used.

➤ Compound semiconductors that are synthesized using elements from 2<sup>nd</sup> and 6<sup>th</sup> group include;

- Cadmium-Selenium(CdSe)
- Cadmium-Tellurium(CdTe)
- Cadmium-Mercury Tellurium (CdHgTe)
- Zinc Sulfer(ZnS).

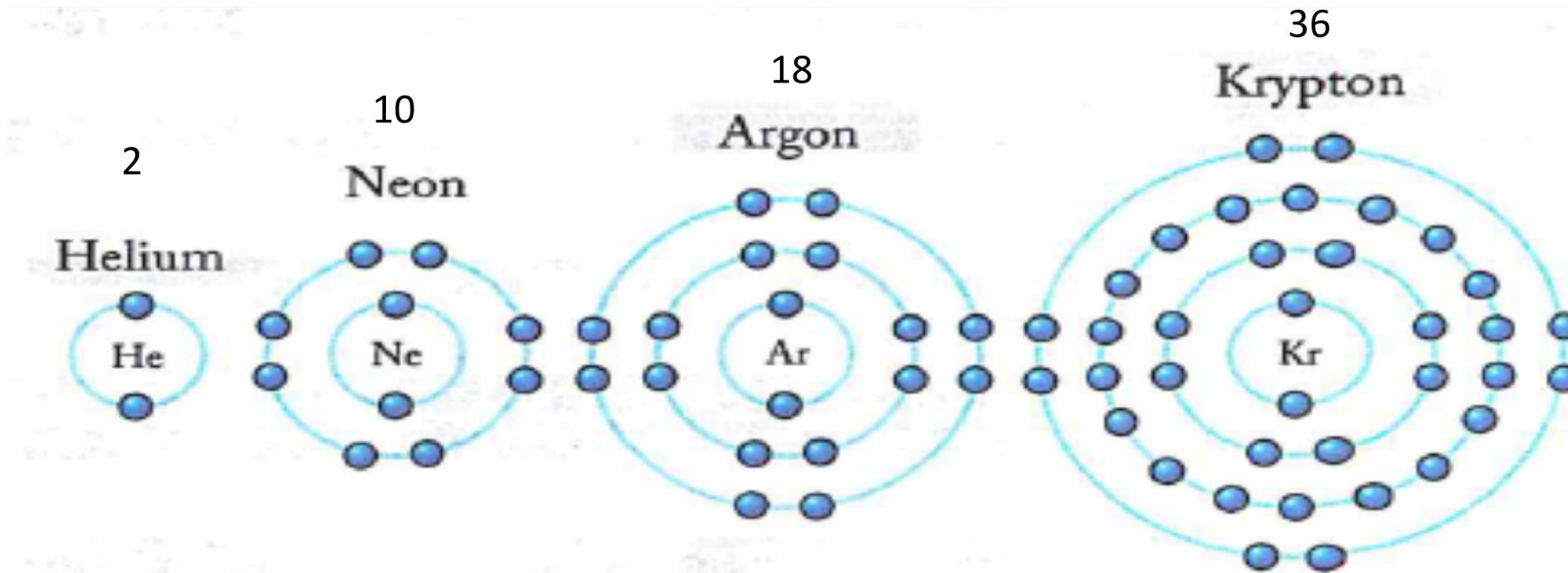
	III	IV	V	VI
	5 <b>B</b> 10.81	6 <b>C</b> 12.01	7 <b>N</b> 14.01	8 <b>O</b> 16.00
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**Ligh Detector Such as photocells are typically made from Insb or CdSe Compounds.**



# ELECTRON BEHAVIOR IN VALANCE SHELLS

Shell or Orbit Number	1	2	3	4	5
Maximum Number of Electrons	2	8	18	32	50



**Figure: Elements with full valance Shells are good insulators**

# GOOD CONDUCTOR

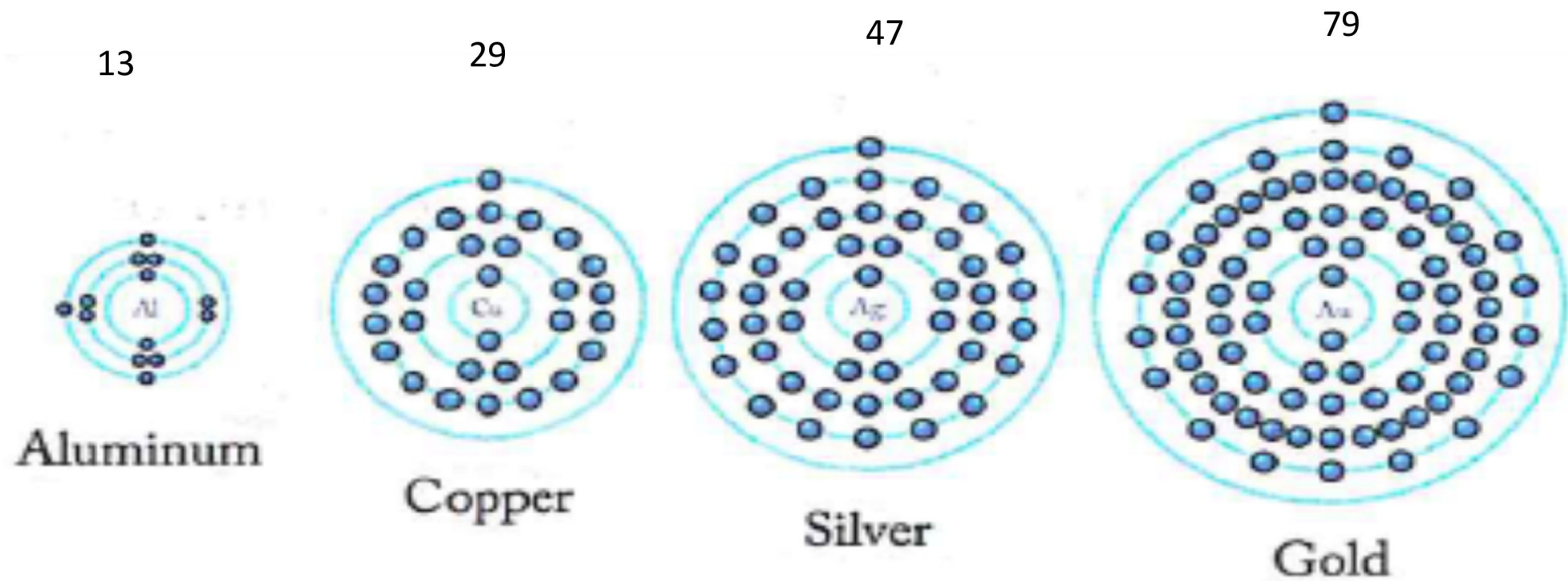
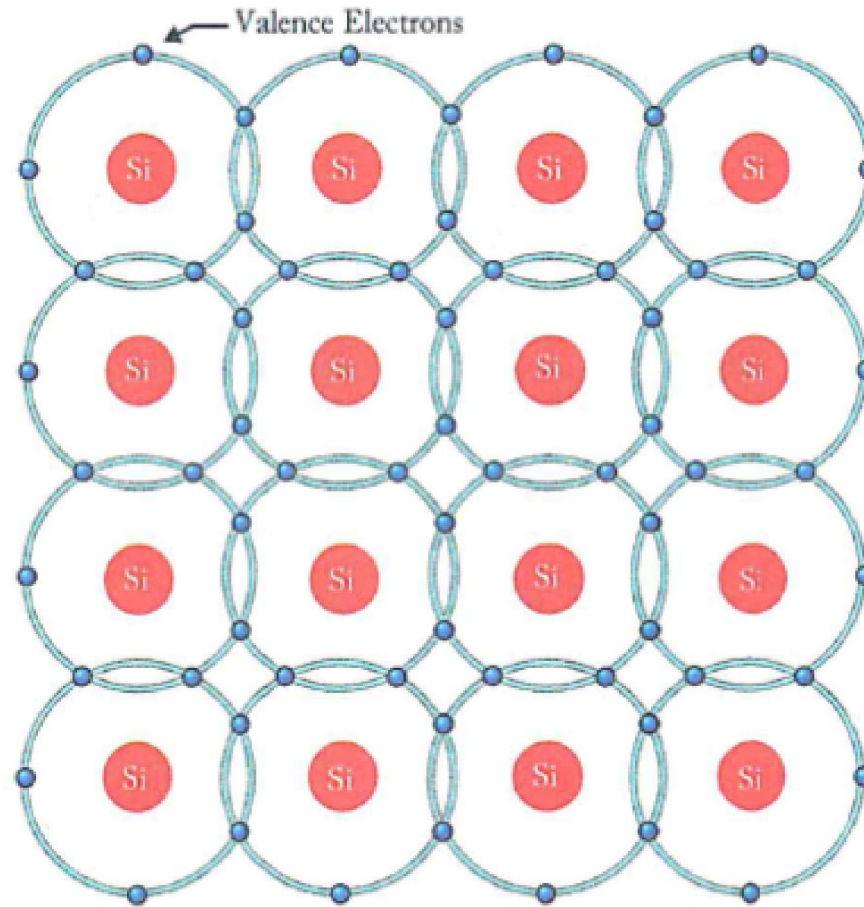


Figure : The Valance shells of elements that are good conductors have 1 or 3 electrons.

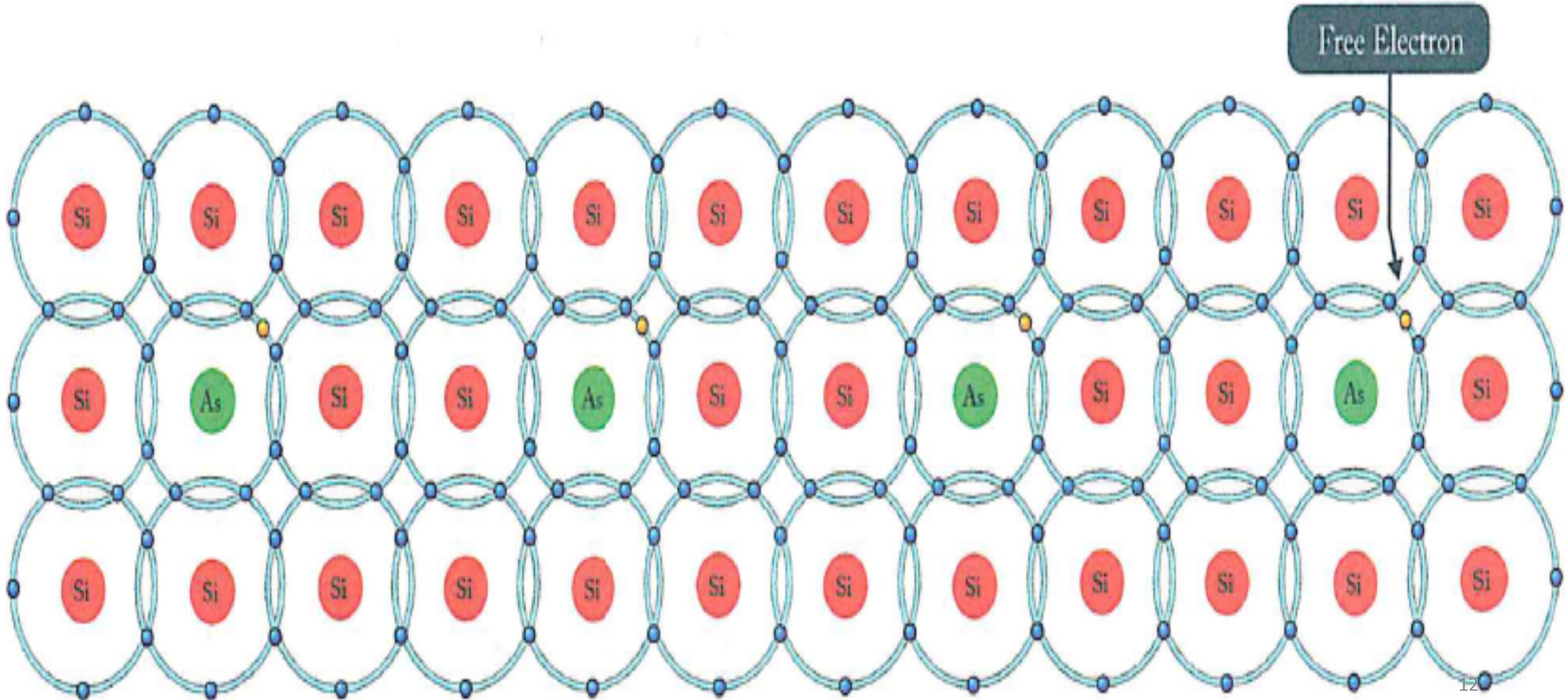
## Silicon : 14 (2-8-4)



**Figure : The Silicon atoms with just the valance shell electrons share.**

## EFFECT OF IMPURITIES ON P AND N TYPE MATERIALS

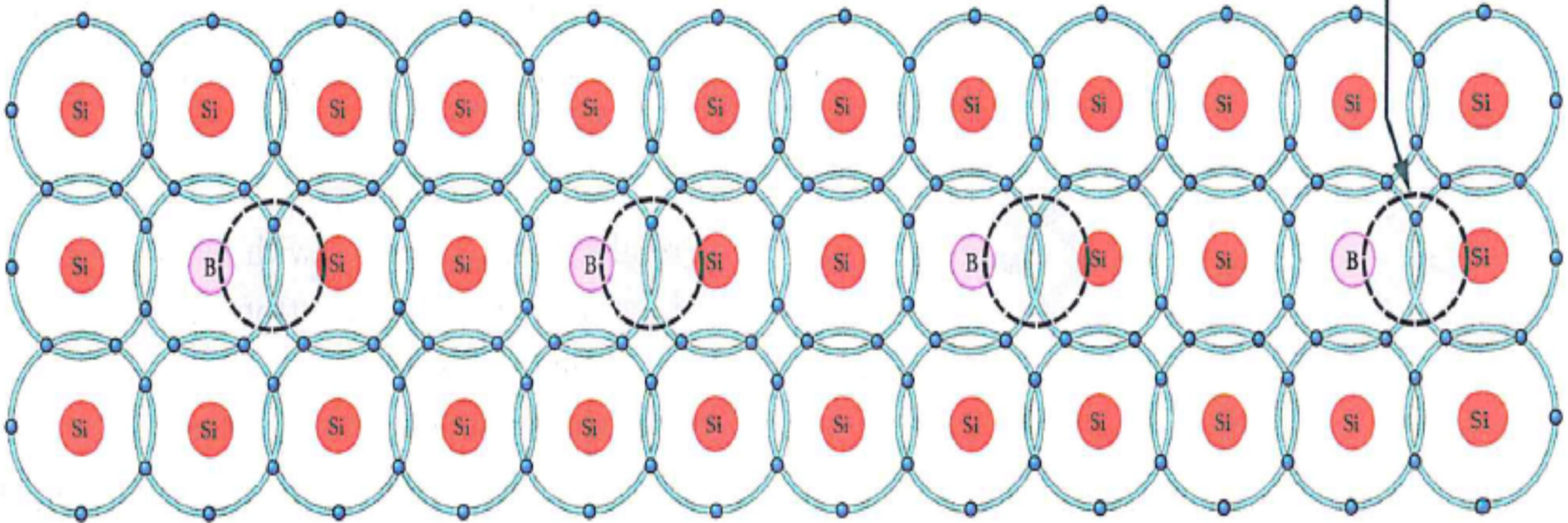
- Silicon in its ultra-pure form is an insulator, it must be transformed into a semi-conductive material by adding some impurities to the silicon- this process is known as **Doping**.



- Arsenic(As), Phosphorus(P) or some other element with five valence electrons in each atom is mixed into Silicon.
- When Silicon is doped with an element or compound containing five electrons in its valence shell, the result is a negatively charged material due to the excess free electrons, and fact that electrons are negatively charged. This is **known as N-type Semiconductor also known as donor Material.**

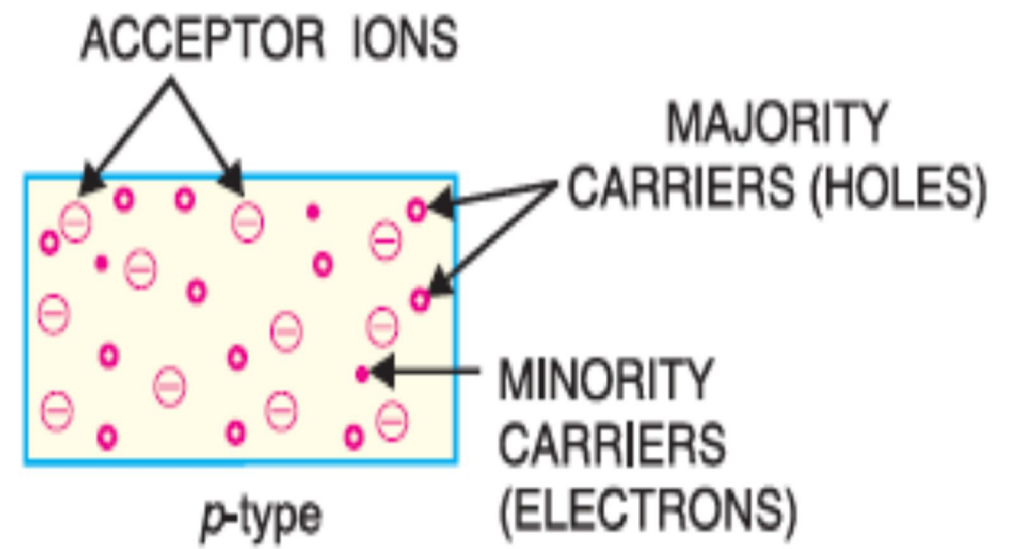
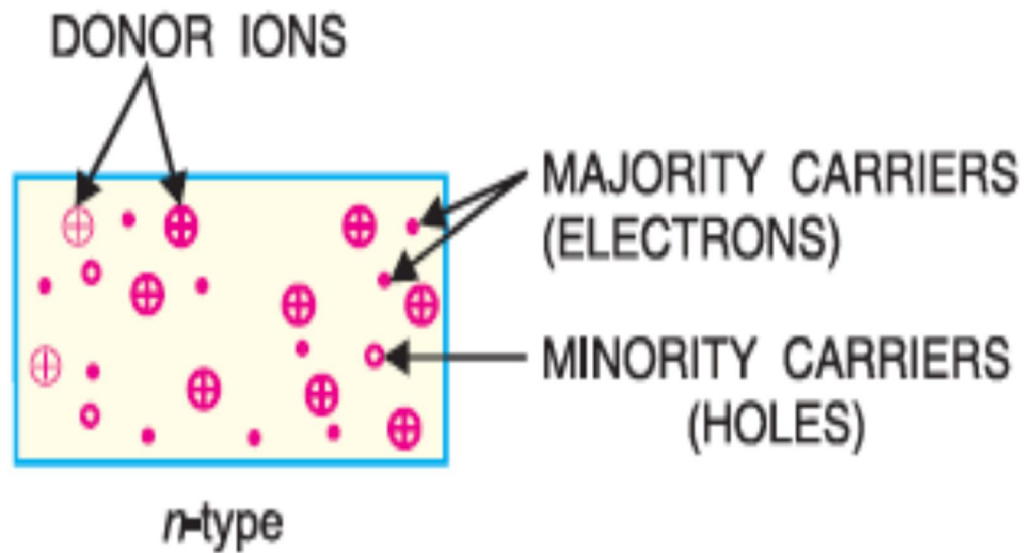
- Doping Silicon can also be performed with an element that has only three valence electrons, such as boron, gallium or indium.
- P-Type Material or Acceptor material.

A "hole" exists because there is no electron in the boron to form covalent bond here.



# MAJORITY AND MINORITY CARRIERS

Material	Majority	Minority
P-Type	Hole	Electrons
N-type	Electron	Hole

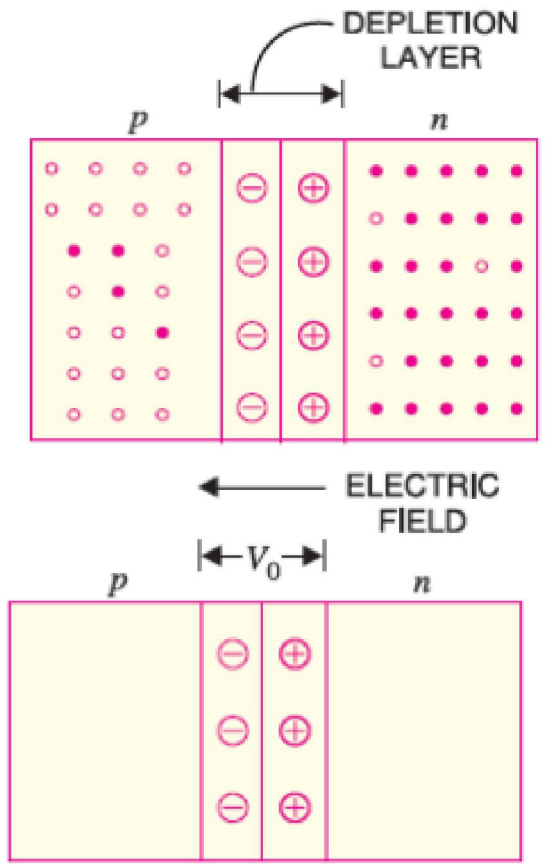


# PN JUNCTIONS

- When a p-type semiconductor is suitably joined to n-type semiconductor, the contact surface is called **PN junction**.
- At the instant of pn-junction formation, the free electrons near the junction in the n region begin to diffuse across the junction into the p region where they combine with holes near the junction.
- The result is that n region loses free electrons as they diffuse into the junction. This creates a layer of positive charges (pentavalent ions) near the junction. As the electrons move across the junction, the p region loses holes as the electrons and holes combine.
- The result is that there is a layer of **negative charges (trivalent ions)** near the junction. These two layers of positive and negative charges form the **depletion region (or depletion layer)**.
- The **term depletion** is due to the fact that near the junction, the region is depleted (i.e. emptied) of charge carriers (free electrons and holes) due to diffusion across the junction.
- It may be noted that depletion layer is formed very quickly and is very thin compared to the n region and the p region.

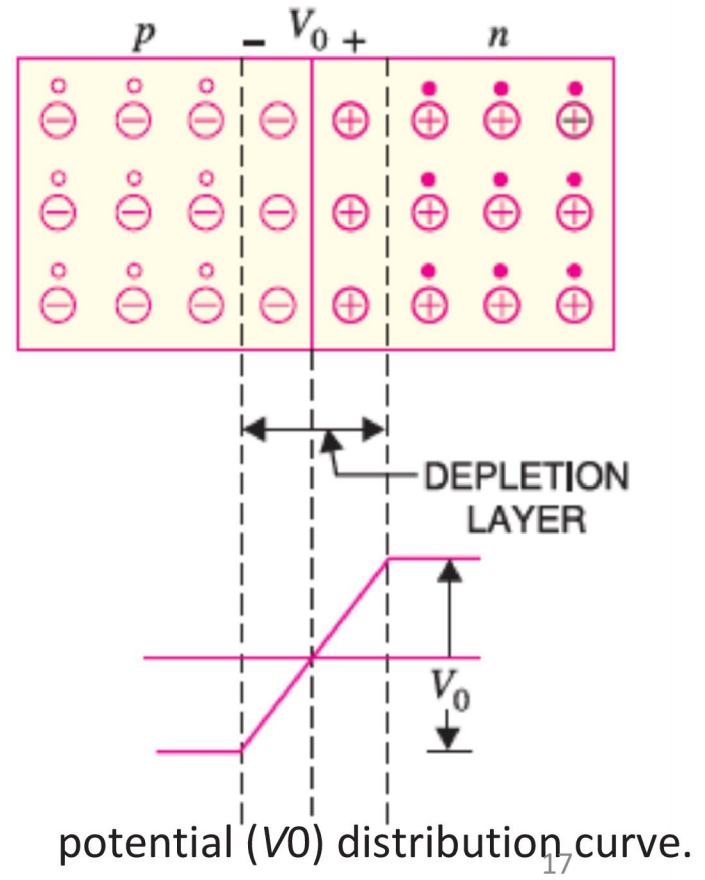


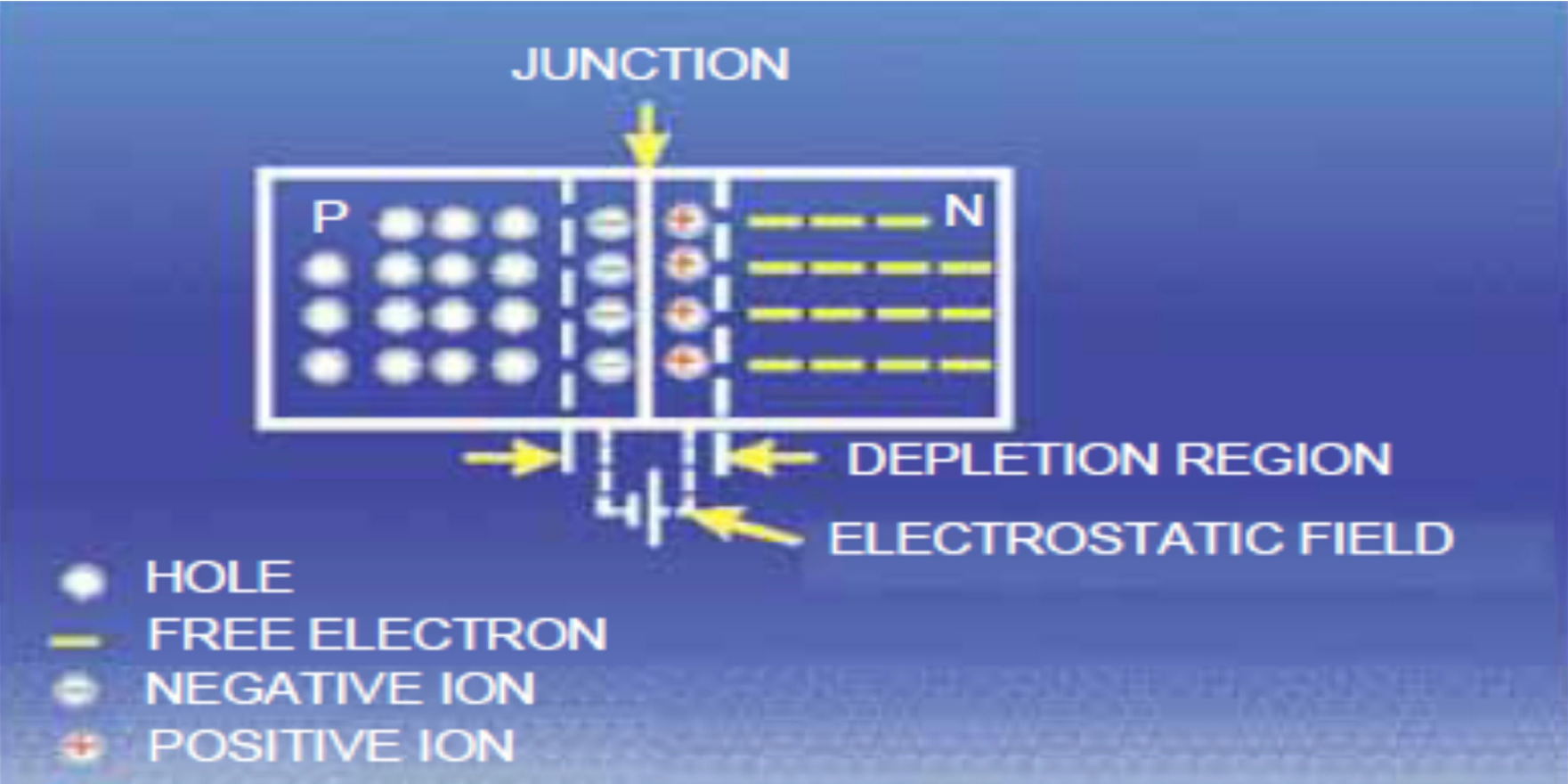
- Once *PN* junction is formed and depletion layer created, the diffusion of free electrons stops. In other words, the depletion region acts as a barrier to the further movement of free electrons across the junction. The positive and negative charges set up an electric field. This is shown by a black arrow in below Fig.
- The electric field is a barrier to the free electrons in the *n*-region. There exists a potential difference across the depletion layer and is called **barrier potential** ( $V_0$ ). The barrier potential of a *pn* junction depends upon several factors including the type of semiconductor material, the amount of doping and temperature.



The typical barrier potential is approximately:

silicon,  $V_0 = 0.7 \text{ V}$  germanium,  $V_0 = 0.3 \text{ V}$

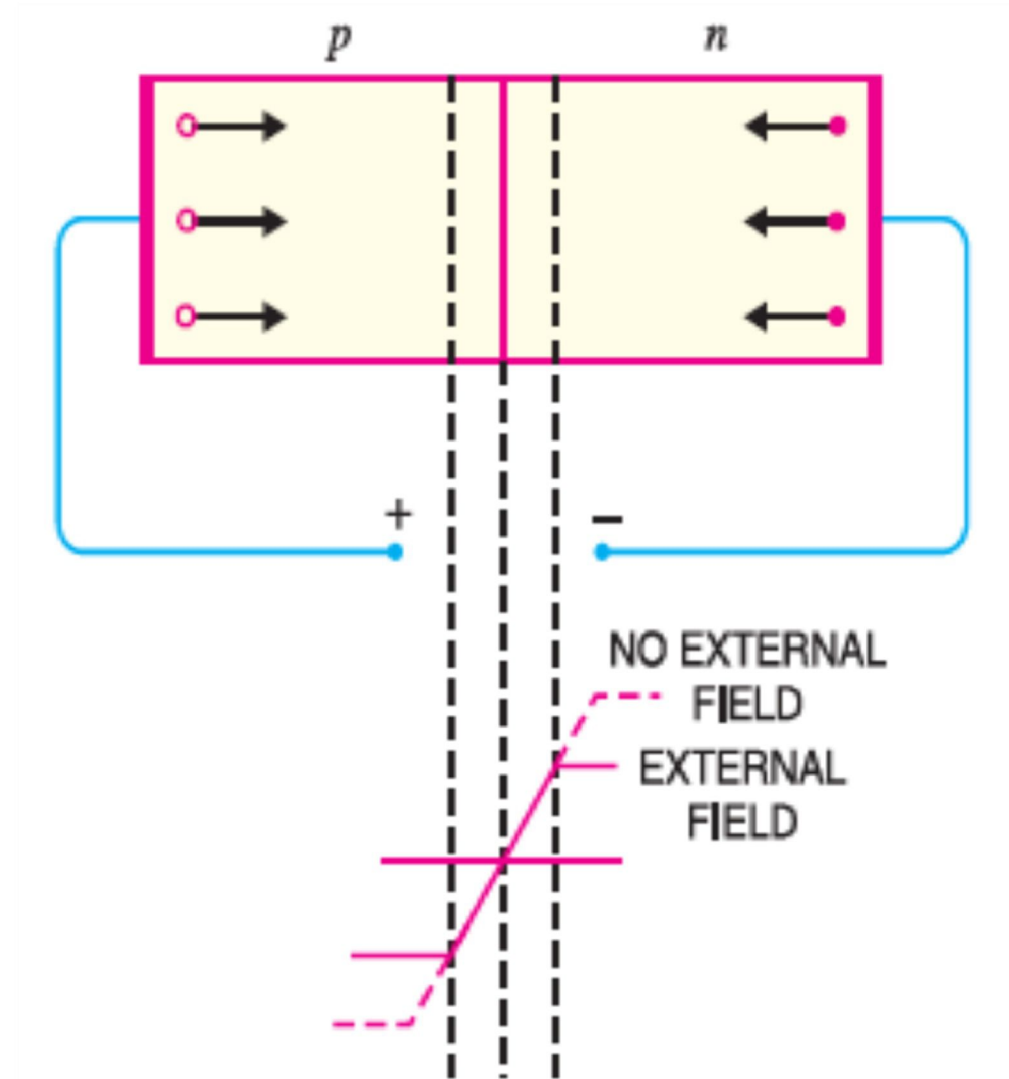




# BIASING A PN JUNCTION

## Forward biasing.

- When external d.c. voltage applied to the junction is in such a direction that it cancels the potential barrier, thus permitting current flow, it is called **forward biasing**.
- To apply forward bias, connect positive terminal of the battery to  $p$ -type and negative terminal to  $n$ -type as shown in Fig.
- The applied forward potential establishes an electric field which acts against the field due to potential barrier.
- Therefore, the resultant field is weakened and the barrier height is reduced at the junction as shown in Fig.
- As potential barrier voltage is very small (0.1 to 0.3 V), therefore, a small forward voltage is sufficient to completely eliminate the barrier.



➤ Once the potential barrier is eliminated by the forward voltage, junction resistance becomes almost zero and a low resistance path is established for the entire circuit. Therefore, current flows in the circuit. This is called *forward current*. With forward bias to *PN* junction, the following points are worth noting :

**(i)** The potential barrier is reduced and at some forward voltage (0.1 to 0.3 V), it is eliminated altogether.

**(ii)** The junction offers low resistance (called *forward resistance,  $R_f$* ) to current flow.

**(iii)** Current flows in the circuit due to the establish